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Chiang et al.

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(54) **METHOD FOR DETECTING SEAM IN FILM**

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(71) Applicant: **Winbond Electronics Corp.**, Taichung City (TW)

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(72) Inventors: **Chih-Yu Chiang**, Taichung City (TW);
Chi-Hung Chan, Taichung City (TW)

(73) Assignee: **Winbond Electronics Corp.**, Taichung City (TW)

(57)

ABSTRACT

A method for detecting a seam in a film is provided. The following process is performed on a film in a first wafer: (a) a scan is performed to obtain a gray level image; (b) a region positioning process is performed on the gray level image to define target regions and a seam region located in each target region; (c) a gray level value of each pixel in each seam region is obtained, and the number of pixels whose gray level values are lower than a gray level threshold value in each seam region is calculated; (d) a pixel quantity threshold value is generated according to the number in each seam region. Then, the process (a) to (c) is performed on a film in a second wafer, and a seam region having the number exceeding the pixel quantity threshold value is determined to be a defect region.

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